

Product / Process Change Notification



N° 2015-149-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Transfer of wafer production, wafer test site and change to copper wire bond for TLE7368E

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **26. February 2016**.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."
- This PCN includes a **Product Discontinuation Notice** (JEDEC STANDARD "JESD48") on page 3/3

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Disclaimer:

If we do not receive any response by the date in the PCN above we consider this as the acceptance of the PCN. After the last order date as stated herein, purchase orders related to the unchanged product(s) cannot be accepted.

In case the customer rejects this PCN this PCN shall be considered a product discontinuation notice (PD).

Product / Process Change Notification



N° 2015-149-A

SUBJECT OF CHANGE: Transfer of wafer production, wafer test site and change to copper wire bond for TLE7368E

PRODUCTS AFFECTED:	TYPE	SP N°	OPN	Package
	TLE7368E	SP000307244	TLE7368EXUMA1	PG-DSO-36
	TLE7368E	SP001094780	TLE7368EXUMA2	PG-DSO-36

REASON OF CHANGE:

Due to continuously raising demand for Infineon automotive products we have to transfer wafer production site and test location to the well-known front end (FE) location Kulim.

Copper wire bonding is part of Infineon's continuous drive to deliver higher performance products. A copper wire enables superior electrical, thermal and reliability performance compared to Au, making it an excellent interconnect solution for automotive packaging.

DESCRIPTION OF CHANGE:	<u>OLD</u>	<u>NEW</u>
<ul style="list-style-type: none"> ■ Wafer production site 	Infineon Technologies AG Regensburg, Germany	Infineon Technologies (Kulim) Sdn. Bhd, Kulim, Malaysia
<ul style="list-style-type: none"> ■ Wafer test site 	Infineon Technologies AG Villach, Austria	Infineon Technologies (Kulim) Sdn. Bhd, Kulim, Malaysia
<ul style="list-style-type: none"> ■ Wire bond 	Gold and copper wire bond	Copper wire bond

PRODUCT IDENTIFICATION:

Wafer lot numbers from Regensburg start with RUxxxxxx and from Kulim start with 1Exxxxxx.
Traceability assured via date code.
SP ordering number is different.

TIME SCHEDULE:

■ Final qualification report:	available	
■ First samples available:	available	
■ Start of delivery:	01-July-2016 or earlier on customer request	
■ Last order date of unchanged product:	31-July-2016	See page 3/3
■ Last delivery date of unchanged product:	31-January-2017	See page 3/3

ASSESSMENT:

No impact on electrical performance. Quality and reliability verified by qualification.
There is no change in form, fit and function.
In general Infineon has a lot of experience with copper wire bonding. As an example TLE7368-2E/-3E are produced with copper wires only.

DOCUMENTATION: N.A.

PRODUCT Replacement

PD15149



referring to PCN N° 2015-149-A

■ Last order date of unchanged product:	2016-07-31
■ Last delivery date of unchanged product	2017-01-31

DISCONTINUED				NEW (REPLACEMENT)			
Device	SP N°	OPN	Package	Device	SP N°	OPN	Package
TLE7368E	SP000307244	TLE7368EXUMA1	PG-DSO-36	TLE7368E	SP001311434	TLE7368EXUMA3	PG-DSO-36
TLE7368E	SP001094780	TLE7368EXUMA2	PG-DSO-36	TLE7368E	SP001311434	TLE7368EXUMA3	PG-DSO-36

If you have any questions, please do not hesitate to contact your local Sales office.